

wherein the step of forming the build-up wiring layer is adapted so that a first wiring layer is formed via a step of forming photosensitive dielectric layer onto the entire surface of the build-up formation surface of the base substrate portion, a via formation step and a step of forming a conductive pattern or patterns onto the photosensitive dielectric layer, and wiring layers of upper layers are formed in succession via similar steps onto the first wiring layer, and

a step of forming solder resist layer and an electrode formation step are implemented to the wiring layer of the uppermost layer to mount high frequency circuit components (parts).

Respectfully submitted,



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